



U.S. Display Consortium

USDC Flexible Display Report

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Table of Contents

Table of Contents		i
Table of Figures		v
Table of Tables		xiv
1.0 Introduction		1-1
1.1 Trends in the Markets for Traditional Paper		1-2
1.1.1 The Costs of Using Paper		1-7
1.2 The Attributes of “Paper-Like Displays”		1-11
1.3 Evaluations of Electronic Paper		1-13
1.3.1 Reflectivity		1-14
1.3.2 Contrast		1-15
1.3.3 Resolution		1-17
1.3.4 Human Response to Electronic Paper		1-18
1.3.5 Writing and Drawing on Electronic paper		1-19
2.0 Markets for Electronic Paper Displays		2-1
2.1 Small Handheld or Wrist-Worn Displays		2-2
2.2 Smart Cards, Tickets and Labels		2-5
2.2.1 Smart Cards		2-5
2.2.2 Smart Tickets and Labels		2-9
2.3 Electronic Books		2-13
2.4 Signs and Information Displays		2-18
2.4.1 Simple Informational Signs		2-18
2.4.2 Advertising Posters and Billboards		2-20
2.4.3 Narrowcasting		2-25
2.4.4 Sales of Traditional Flat Panel Displays		2-27
2.5 Embedded Displays		2-30
2.6 Military Applications		2-32
2.6.1 U. S. Army Announces Establishment of Flexible Display Center at Arizona State University		2-32
2.6.2 Immersive Displays		2-35
3.0 Bistable Reflective Displays		3-1
3.1 Physical Modulation		3-2
3.1.1 Encapsulated Electrophoretic Displays		3-2
3.1.1.1 Monochrome Performance		3-3
3.1.1.2 Color Performance		3-3
3.1.1.3 Video Performance		3-5
3.1.1.4 Resolution		3-7
3.1.1.5 Gray Scale and Stability		3-7
3.1.1.6 Backplane Requirements		3-8
3.1.1.7 EPD on Flexible Substrates		3-9
3.1.1.8 Roadmaps for Development and Products		3-10
3.1.2 Microcup™ Electrophoretic Displays		3-12
3.1.2.1 Formation of Microcups		3-12
3.1.2.2 Driving Microcup™ Displays		3-13
3.1.2.3 Full Color Microcup™ Displays		3-14
3.1.2.4 Environmental Stability		3-15
3.1.3 In-Plane Electrophoretic Displays		3-17
3.1.4 Quick-Response Liquid Powder Display		3-20
3.1.5 Rotating Balls		3-21
3.1.6 Electrowetting		3-25

3.2	Electrochromic Displays	3-28
3.2.1	Nanochromic Displays	3-29
3.2.2	pH Indicator Dye Displays	3-30
3.3	Mechanical Modulation	3-33
3.3.1	Interferometric Modulation	3-33
3.3.2	Electro-Polymeric Shutter Display	3-35
3.4	Bistable Liquid Crystal Displays	3-37
3.4.1	Cholesteric Displays	3-37
3.4.2	Polymer Stabilized Cholesteric Displays	3-40
3.4.3	Surface-Stabilized Cholesteric Texture Displays	3-42
3.4.4	Bistable Nematic Displays	3-43
3.4.4.1	Nemoptic	3-43
3.4.4.2	Zenithal Bistable Display (ZBD)	3-47
4.0	Emissive Displays	4-1
4.1	Organic Light Emitting Diodes	4-1
4.1.1	Small Molecule OLEDs	4-2
4.2	Plasma Display Panels	4-10
4.2.1	Plasma Tube Arrays	4-10
4.2.2	The Fiber-Driven Plasma Display	4-11
4.2.3	Plasma Microspheres	4-14
5	Transmissive Liquid Crystal Displays	5-1
5.1	Twisted Nematic Displays	5-1
5.1.1	Passive Matrix Panels on Flexible Substrates	5-1
5.1.2	Active Matrix LCD on Plastic Substrates	5-5
5.2	Ferroelectric Displays	5-6
6	Materials	6-1
6.1	Substrates	6-1
6.1.1	Process Temperature Tolerance	6-3
6.1.1.1	Coefficient of Thermal Expansion	6-7
6.1.1.2	Rigidity	6-8
6.1.1.3	Water Uptake	6-9
6.1.1.4	Optical Transparency	6-9
6.1.1.5	Optical Birefringence	6-11
6.1.1.6	Porosity	6-11
6.1.1.7	Chemical Resistance	6-12
6.1.1.8	Surface Roughness	6-13
6.2	Barrier Coatings for Flexible Substrates	6-15
6.3	Thin Film Encapsulation	6-20
6.3.1	Hybrid Multi-layer Films	6-20
6.3.1.1	Inorganic Films	6-23
6.4	Ultra-Thin Glass	6-24
6.5	Metal Foils	6-26
6.6	Sealants	6-28
6.7	Desiccants	6-31
7	Electronic Backplanes	7-1
7.1	Segmented Displays and Passive Matrix	7-1
7.2	Amorphous Silicon TFTs	7-2
7.2.1	Digital Lithography	7-8
7.3	Poly-Silicon	7-10
7.3.1	Poly-Si TFTS on Metal Foils	7-13
7.3.2	Transfer Techniques	7-14

7.4	Organic TFTs	7-19
7.4.1	Pentacene TFTs	7-19
7.4.2	Polyarylamines	7-29
7.4.3	Thiophenes	7-32
7.5	Conductors	7-36
7.5.1	ITO	7-36
7.5.2	Carbon Nanotubes	7-39
7.5.3	Thin Metal Films	7-42
7.5.4	Bus Lines	7-43
7.6	Power Sources	7-45
8	Manufacturing Processes	8-1
8.1	Ink-Jet Printing	8-2
8.1.1	Ink-Jet Heads	8-3
8.1.2	Inks	8-10
8.1.2.1	Matching Solvents to the Active Materials	8-10
8.1.2.2	Compatibility with Print Heads	8-10
8.1.2.3	Drop Dynamics	8-11
8.1.3	Film Morphology and Substrate Interactions	8-11
8.1.3.1	Pixel Definition - Barriers	8-12
8.1.3.2	Surface Engineering	8-15
8.1.4	Printer Systems	8-19
8.1.5	Test Results	8-23
8.2	Transfer Processes	8-26
8.2.1	Laser Induced Thermal Imaging (LITI) Process	8-26
8.2.1.1	A New Strategy for Laser-Induced Thermal Imaging (LITI)	8-29
8.2.2	Flat Bed Scanners with Laser Diodes	8-30
8.2.3	Thermal Multi-Layer Patterning Process	8-32
8.3	Other Printing Methods	8-34
8.4	Traditional High-Speed Printing Processes	8-36
8.4.1	Screen Printing	8-37
8.4.2	Flexography	8-38
8.4.3	Gravure	8-39
8.4.4	Offset Lithography	8-40
9	Roll To Roll Processing	9-1
9.1	Web Handling	9-3
9.1.1	Errors and Defects	9-5
9.1.1.1	Web Positioning	9-5
9.1.1.2	Web Damage	9-7
9.2	Process Set	9-10
9.2.1	Substrate Cleaning and Preparation	9-11
9.2.2	Coatings	9-12
9.2.3	Lithography	9-15
9.2.4	Patterned Deposition	9-19
9.2.5	In-Line Measurement Tools	9-21
9.3	Strategic Development Efforts	9-25
9.3.1	USDC Infrastructure Support	9-25
9.3.1.1	Web Handling	9-25
9.3.1.2	Linear Sources	9-27
9.3.1.3	Lithography	9-27
9.3.1.4	Cost Models	9-28

9.3.2	Center for Advanced Microelectronics Manufacturing (CAMM)	9-30
9.3.2.1	Objectives for Technology Development:	9-30
9.3.2.2	Approach	9-31
9.3.2.3	Schedule	9-31
9.3.3	European Union Projects	9-32
9.3.3.1	ROLLED	9-32
9.3.3.2	POLYAPPLY	9-33
9.3.3.3	SHIFT	9-35
9.3.3.4	CONTACT	9-37
9.3.3.5	NANOPAGE	9-38
9.3.3.6	FLEXIDIS	9-39
9.3.4	Photovoltaics	9-40
9.3.4.1	Iowa Thin Film Technologies	9-41
9.3.4.2	Unisolar	9-43
9.3.5	Radio Frequency Identification Tags	9-46
9.3.5.1	PolyIC	9-47
9.3.5.2	Alien Technology	9-47

Table of Figures

Figure 1.1 Impact of New Printing Technologies	1-2
Figure 1.2 Consumption and Production of Printing Paper in North America	1-2
Figure 1.3 Growth in Paper Use by Country 1992-2000	1-3
Figure 1.4 World Paper Consumption	1-3
Figure 1.5 U. S. Plants with Offset Presses Categorized by Employee Number	1-4
Figure 1.6 U. S Printing Industry: Page Volume by Market Segment	1-5
Figure 1.7 U. S. Annual Book Sales	1-5
Figure 1.8 U. S. Magazine Ad Pages (Seasonally Adjusted)	1-5
Figure 1.9 Trends in Leisure-Time "Information" Gathering	1-6
Figure 1.10 Predicted Replacement of Traditional Printing by 2010	1-6
Figure 1.11 U.S. Printing and Writing Tonnage	1-7
Figure 1.12 U.S. Print on Demand Market	1-7
Figure 1.13 Notebook Computer Screen and Magazine in (a) Bright and (b) Dim Ambient Light	1-13
Figure 1.14 Comparison of Reflective LCD and iMoD Display	1-13
Figure 1.15 Relative Reflectance of Various Media	1-14
Figure 1.16 Competition between Diffuse and Specular Reflection	1-15
Figure 1.17 Relative Contrast of Various Media	1-15
Figure 1.18 Checkerboard Measurement of Contrast Ratio	1-16
Figure 1.19 Magnified Photo of Notebook Display Screen	1-17
Figure 1.20 Search Times to Locate Character Strings on Computer Screens and Paper	1-17
Figure 1.21 Dependence of Reading Rates on Dot Pitch and Font Size	1-17
Figure 1.22 Time to Visibility of Various Displays in Different Ambient Lighting Levels	1-18
Figure 1.23 Reading Speeds and Fatigue Levels for Fixed and Free Media	1-19
Figure 1.24 Prototype Electronic Sketch Pad	1-20
Figure 2.1 Concepts for Conformal Displays in Handheld Devices	2-2
Figure 2.2 Growth of Commercial Biosensor Market	2-3
Figure 2.3 Examples of Commercial Glucose Sensors	2-3
Figure 2.4 Personal Health Monitor with Conformable Display	2-4
Figure 2.5 Prototype Smart Cards with Electrophoretic Displays	2-5
Figure 2.6 Prototype smart card with LEP display	2-5
Figure 2.7 Price Sensitivity of Potential Market Size for Smart Labels	2-6
Figure 2.8 Conceptual Personal Pocket Assistant	2-6
Figure 2.9 Smart Card with User-Controlled Display	2-8
Figure 2.10 Smart Greeting Cards	2-9
Figure 2.11 Smart Tickets and Smart Labels	2-9
Figure 2.12 Smart Label for Blood Bag	2-10
Figure 2.13 Smart Skin Patch	2-11
Figure 2.14 Shelf Labels	2-12
Figure 2.15 Price Optimization Systems	2-12
Figure 2.16 Electronic Shelf-Label with PDLC Display	2-13
Figure 2.17 Sigma Book from Matsushita	2-14
Figure 2.18 EBR-1000 LIBRIe Book Reader from Sony	2-15
Figure 2.19 Educational e-books from LeapFrog	2-17
Figure 2.20 Informational Display in Airports	2-19
Figure 2.21 Informational Sign with Electrophoretic Display	2-20
Figure 2.22 Monochrome Informational Signs	2-20
Figure 2.23 Promotional Signs with Limited Color	2-20
Figure 2.24 Promotional Banners	2-21
Figure 2.25 Support System for Digital Signs	2-21

Figure 2.26 Examples of Conformal Billboard Displays	2-24
Figure 2.27 Traveling Billboards	2-24
Figure 2.28 Simple Mechanical “Dynamic” Display	2-25
Figure 2.29 LED Displays Shine Brightly by Day and Night	2-25
Figure 2.30 Digital Ink Technology on Billboards in the U. K. and U.S.	2-26
Figure 2.31 Estimated Market for Mid-Sized Electronic Posters	2-26
Figure 2.32 Predicted Growth of Narrowcasting Industry	2-27
Figure 2.33 Structure of the Narrowcasting Industry	2-27
Figure 2.34 Plasma Screens Used to Show Simple Static Images	2-28
Figure 2.35 Public Display Sales by Technology (1000 units)	2-28
Figure 2.36 Public Display Pricing Forecasts	2-29
Figure 2.37 Predicted Electronic Signage Display Revenue (\$M)	2-29
Figure 2.38 Predicted Electronic Signage Display Market (units)	2-30
Figure 2.39 Predicted Electronic Signage Display Prices	2-30
Figure 2.40 Concept of Rollable Display	2-33
Figure 2.41 Center Facility Viewed from ASU Research Park Entrance	2-34
Figure 2.42 Collaborations and Output from the Flexible Display Center	2-35
Figure 2.43 Anticipated Prototype Displays from the Center	2-35
Figure 2.44 Evolution of Personal Displays for Military Applications	2-36
Figure 2.45 Prototype Cholesteric Display for Military Applications	2-36
Figure 2.46 Concepts of Flexible Immersive Displays for Training Simulations	2-37
Figure 2.47 Concept and Prototype of Immersive Desktop Display	2-37
Figure 3.1 Microencapsulated Electrophoretic Cells with Pigments of a Single Color	3-2
Figure 3.2 Microencapsulated Electrophoretic Cells with Two Types of Pigment	3-2
Figure 3.3 70 μ m Electrophoretic Capsules	3-3
Figure 3.4 Color EPDs without Color Filters	3-4
Figure 3.5 Patterned Deposition of Microcapsules	3-4
Figure 3.6 Mechanism and Photograph of Color EPDs in Shutter Mode	3-4
Figure 3.7 Reflectivity of Prototype Color EPD and High-gain Reflective LCD	3-5
Figure 3.8 Dynamic Range of Fast EPD as a Function of Voltage and Pulse Length.	3-5
Figure 3.9 Trade-Off between Contrast Ratio and Response Time	3-6
Figure 3.10 Improvement in the Response of Microencapsulated EPD over Time	3-6
Figure 3.11 Contrast Ratio as a Function of Effective Resolution	3-7
Figure 3.12 Gray Scale Stability	3-7
Figure 3.13 Current passed by pentacene TFTs; A. I-V characteristics; B. On/off ratio for 64 pixels	3-8
Figure 3.14 4.7” QVGA AM-electrophoretic display with organic TFTs	3-9
Figure 3.15 Comparison of the Thickness of E-Ink and AMLCD Displays	3-9
Figure 3.16 E Ink Displays on Plain Paper and Tyvek	3-10
Figure 3.17 Potential Applications for Encapsulated EPD Displays	3-10
Figure 3.18 Application Roadmap for Encapsulated EPD Displays in E-Books	3-11
Figure 3.19 Collaboration Between E-Ink, Philips and Toppan to Develop AM-EPDs	3-11
Figure 3.20 Roll-to-Roll Fabrication of Microcup™ Electrophoretic Display	3-12
Figure 3.21 Embossed Microcups to Hold Electrophoretic Material	3-12
Figure 3.22 One-pass filling and sealing process	3-13
Figure 3.23 Operation of Microcup™ Electrophoretic Display	3-13
Figure 3.24 Direct-drive Electrophoretic Display with Curved Electrodes	3-14
Figure 3.25 Prototype of Active Matrix EPD	3-14
Figure 3.26 Motion of Ink Balls in Dual Mode Electrophoretic Display	3-15
Figure 3.27 Predicted Color Gamut of Dual-Mode Electrophoretic Displays	3-15
Figure 3.28 Water Immersion Tests of Electrophoretic Display	3-16

Figure 3.29 Structure of Full-Color In-Plane EPD	3-17
Figure 3.30 Process Flow to Manufacture Embedded Collection Electrodes	3-17
Figure 3.31 Introduction of Directed Reflector	3-18
Figure 3.32 Color Patterns from In-Plane EPD	3-18
Figure 3.33 Dependence of Reflectivity on Direction of Incident Light	3-19
Figure 3.34 Spectrum of Reflected Light for (a) EPD and (b) LCD	3-19
Figure 3.35 Color Gamut of EPD and Reflective LCD	3-20
Figure 3.36 Pixel Operation and Hexagonal Rib Structure in Quick-Resp. Liquid Powder Display	3-20
Figure 3.37 Effect of Bending on Reflectivity of Quick-Response Liquid Powder Display	3-21
Figure 3.38 Operation of Gyricon Displays	3-21
Figure 3.39 Photograph of the Intersection of Four Pixels in a Gyricon Display	3-22
Figure 3.40 Variation of Reflectance with Voltage	3-22
Figure 3.41 Variation of Ball Rotation Time with Size and Voltage	3-22
Figure 3.42 Critical Steps in Gyricon Display Production	3-23
Figure 3.43 Backplane Options for Gyricon Displays	3-24
Figure 3.44 Market Entry Strategy for Gyricon Displays	3-24
Figure 3.45 Early Installations of Gyricon Signs	3-24
Figure 3.46 Pixel Operation in Electrowetting Display	3-25
Figure 3.47 Structure of Electrowetting Display	3-25
Figure 3.48 Response Speed and Switching Lifetime	3-26
Figure 3.49 Two Independent Shutters in Each Cell	3-26
Figure 3.50 Structure and Gamut of Full-Color Electro Wetting Display	3-26
Figure 3.51 Manufacturing Process	3-27
Figure 3.52 Monochrome Electrochromic Display Structure	3-28
Figure 3.53 Process Steps for the Manufacture of the Monochrome Electrochromic Display	3-28
Figure 3.54 Structure of Electrochromic Display	3-29
Figure 3.55 Dependence of Switching Speed on Drive Voltage	3-29
Figure 3.56 Variation of Contrast Ratio with Viewing Angle	3-30
Figure 3.57 Technology and Application Roadmap for Nanochromic Displays	3-30
Figure 3.58 Structure of Commotion™ Printed Displays	3-31
Figure 3.59 Two Examples of Products with Commotion Displays	3-32
Figure 3.60 Structure of Monochrome and Full-Color iMoDTM Pixels	3-33
Figure 3.61 Reflectance of iMoD Color Display Compared to TFT LCDs in PDAs	3-34
Figure 3.62 Iridigm Prototypes for Cell Phones and Navigation Displays	3-35
Figure 3.63 Operation of Electro-Polymeric Shutter Display	3-35
Figure 3.64 Layer Structure of Cholesteric Displays	3-37
Figure 3.65 Bistable Modes of Cholesteric Liquid Crystals	3-37
Figure 3.66 Bragg Reflection Tuned to the Red	3-38
Figure 3.67 Color from Cholesteric Materials	3-38
Figure 3.68 Black and White Cholesteric Displays	3-39
Figure 3.69 Gray Scale Textures in Cholesteric Displays	3-39
Figure 3.70 Dependence of Update Speed on Temperature	3-40
Figure 3.71 Cholesteric PDLC Display on Plastic Substrate	3-40
Figure 3.72 Deposition and Effect of Co-Deposited Dark Layer	3-41
Figure 3.73 Variation of Switching Voltage with Bending Radius	3-42
Figure 3.74 All-Polymer SSCLT Display	3-42
Figure 3.75 Operation of the Bistable Nematic Cell	3-43
Figure 3.76 State Selection Method in BiNem Displays	3-44
Figure 3.77 Contrast Ratio Contours and Photograph of Reflective BiNem Display	3-45
Figure 3.78 Magnified Picture Showing the Curtain Effect to Achieve Gray Scale	3-45
Figure 3.79 Prototype Color Panels with Bistable Nematic LCDs	3-46

Figure 3.80 Manufacturing Process Flow for BiNem and Standard STN Panels	3-46
Figure 3.81 Polyimide Deposition and Rubbing Processes	3-47
Figure 3.82 Clean Room Requirements for Particulate Control	3-47
Figure 3.83 Two Modes of the Liquid Crystal in the Zenithal Bistable Display	3-48
Figure 3.84 Grating Fabrication Techniques	3-48
Figure 3.85 Completed Gratings	3-48
Figure 4.1 First Prototypes of OLED Display on a Flexible Substrate	4-1
Figure 4.2 Lifetime Tests of PHOLED Pixels on Several Substrates	4-2
Figure 4.3 I-V characteristics and Luminous Efficacy Before and After Life Test	4-3
Figure 4.4 Results of 500 hour storage test of OLEDs under 60°C, 95%RH	4-4
Figure 4.5 Voltage dependence and decay of luminance in OLED displays on plastic and glass substrates in DC mode	4-5
Figure 4.6 OLED films wrapped around a pen	4-5
Figure 4.7 Schematic structure of the flexible OLED display from NHK	4-6
Figure 4.8 Molecular structures of the red and blue phosphorescent emitters	4-6
Figure 4.9 CIE coordinates of red, green and blue emissions from phosphorescent polymer display	4-7
Figure 4.10 L-V characteristics of the blue, red and white phosphorescent polymer LEDs	4-7
Figure 4.11 Production System for Polymer OLEDs	4-8
Figure 4.12 40" Prototype Polymer OLED Panel	4-8
Figure 4.13 17" Prototype OLED TV	4-9
Figure 4.14	4-10
Figure 4.15 Simple Cell Structure for Plasma Tube (Ishimoto et al)	4-10
Figure 4.16 Luminous Efficacy of Plasma Tubes with Various Discharge Gaps (Ishimoto et al)	4-11
Figure 4.17 Luminous Efficacy of Test Tube with 0.4 mm Discharge Gap (Ishimoto et al)	4-11
Figure 4.18 Schematic of the Fiber Channel Plasma Display (Moore)	4-12
Figure 4.19 SEM Micrographs of Top (A) and Bottom (B) Fibers (Moore)	4-12
Figure 4.20 Schematic of the Fiber-Based Plasma Addressed Display (Moore)	4-13
Figure 4.21 Photograph of a Fiber-Based Plasma Addressed Electronic Paper Display Prototype (Moore)	4-14
Figure 4.22 Concept of IsoPix™ Display Based upon Hollow Microspheres (Johnson)	4-14
Figure 4.23 Prototype of Plasma-Sphere™ Display (Johnson)	4-15
Figure 5.1 Pixel-Isolated LC Structure Before and After Patterning	5-1
Figure 5.2 Two-step Photo-Polymerization of Paintable LCDs	5-2
Figure 5.3 Single Exposure Photo-Polymerization of Paintable LCDs	5-2
Figure 5.4 Two Forms of Paintable LCDs with TCF Polarizers	5-3
Figure 5.5 Design of Transflective STN Display	5-3
Figure 5.6 Prototype Flexible CSTN Display	5-5
Figure 5.7 Structure and Photograph of Flexible Ferroelectric LCD	5-6
Figure 5.8 Voltage Dependence of Transmission in FLC Display	5-6
Figure 5.9 Prototype 17" Ferroelectric Display	5-7
Figure 6.1: Glass Transition and Melting Temperatures for Selected Plastics	6-4
Figure 6.2 Thermal Expansion of Heat Stabilized PEN and Unstabilized PET	6-4
Figure 6.3: Polyester Film Formation Process	6-5
Figure 6.4: Thermo-Mechanical Tests of High-Heat Lexan®	6-5
Figure 6.5: Processing Temperatures for Plastic Substrates	6-6
Figure 6.6: Resistivity and optical transmission of ITO as a function of deposition temperature	6-7
Figure 6.7: Thermal Expansion of PC, PES and Fiber Reinforced Plastic	6-8
Figure 6.8: Dependence of Stiffness on Temperature for PET and PEN	6-9
Figure 6.9: Elastic Modulus of PC, PES and Fiber Reinforced Plastic	6-9
Figure 6.10: Optical Transmission of Uncoated Lexan	6-10

Figure 6.11: Optical Transmission of Lexan with Protective Coating and ITO Film	6-10
Figure 6.12: Optical Transmission of Teonex Q65 Without and With Coatings	6-10
Figure 6.13: Transmission of Tosoh's OPS compared to PES	6-11
Figure 6.14: Optical Transmission of Fiber Reinforced Plastic	6-11
Figure 6.15: Effects of Stress on Retardation in OPS and PES	6-12
Figure 6.16: Calcium test for detecting slow permeation of O ₂ or H ₂ O through films	6-13
Figure 6.17: Typical Surface Conditions of Industrial Grade PEN	6-14
Figure 6.18: Typical Surface Conditions of Teonex ® Q65	6-15
Figure 6.19: Water Permeation of Plastic Materials and OLED Requirements	6-16
Figure 6.20: Improvements in Permeability of Doped SiC:H Coatings	6-17
Figure 6.21: Smoothing Effect of Barrier Coatings	6-18
Figure 6.22: Water Damage through Hybrid Coatings with Varying Numbers of Pairs	6-18
Figure 6.23 Permeation through Single and Double Film Pairs	6-19
Figure 6.24: Defect Positions in Multilayer Barriers	6-19
Figure 6.25 Graded Barrier Layer Structure and its Transmissivity	6-20
Figure 6.26 Moisture Permeation Rate for Graded Barrier Layer Structures	6-20
Figure 6.27 OLED Shelf Lifetime Test (at 23°C / 50% RH)	6-21
Figure 6.28: Barix™ Film Encapsulation Process	6-22
Figure 6.29: Transmission through Ca encapsulated by Barix films at 600C, 70% RH	6-23
Figure 6.30: Barix™ Encapsulation over OLED Structures	6-23
Figure 6.31: Prototype Encapsulation Tool	6-24
Figure 6.32: Web Coater Barrier Deposition System	6-24
Figure 6.33: Step Coverage of NON on Structures with Undercuts	6-25
Figure 6.34: Optical Transmission of Plastic Substrate with Inorganic Multilayer Films	6-25
Figure 6.35: Flexibility of ultra-thin glass	6-26
Figure 6.36: Bend radius and allowable stress for thin glass	6-26
Figure 6.37: Ultra-Thin Glass with Polymer Coating	6-27
Figure 6.38: AM-PLED Backplanes on Flexible Glass	6-27
Figure 6.39: Dependence of water vapor permeation on seal width	6-30
Figure 6.40 Moisture Permeation Rate for Various Sealant Formulations	6-31
Figure 6.41 Water Uptake for Various Sealant Formulations	6-31
Figure 6.42 Die Shear Strength for Various Sealant Formulations	6-32
Figure 6.43: Absorption of water by various desiccants from vapor at 250C	6-33
Figure 6.44: Edge growth with differing desiccant applications	6-34
Figure 6.45: Effect of raising the temperature to 850C on wet desiccant	6-34
Figure 7.1: Structure of OLED Pixel with a-Si TFTs Fabricated at 1500C	7-2
Figure 7.2 a-Si TFTs at the four corners of the array	7-3
Figure 7.3: Performance of a-Si TFTs Fabricated at 1500C	7-3
Figure 7.4: Pixel Circuits for Active Matrix Displays and Image Sensors	7-4
Figure 7.5: TFT Structure and Completed Backplane on Kapton	7-4
Figure 7.6: 5-Mask Process for a-Si TFTs on Plastic	7-5
Figure 7.7: a-Si TFT and OLED Pixel Structures	7-5
Figure 7.8: I-V Characteristics of a-Si TFTs on Plastic	7-6
Figure 7.9: Dependence of OLED Currents on Data Input and Operational Lifetime	7-7
Figure 7.10: Processing scheme for a-Si TFTs on PES	7-8
Figure 7.11: New Methods for Fabrication of Large-Area Electronics	7-9
Figure 7.12: I-V Characteristics of a-Si TFTs produced by Digital Lithography	7-9
Figure 7.13: Temperature rises in the Si and SiO ₂ layers and the underlying substrate during annealing by short laser pulses	7-11
Figure 7.14: Flexible Poly-Si Backplane after Delamination from 6" Wafer	7-11
Figure 7.15 I-V characteristic of n-channel TFTs made by ULTPS process	7-12

Figure 7.16: Characteristics of pMOS Device Produced by ULTPS Processing	7-12
Figure 7.17: Pixel Electronics and Driver ICs for p-Si TFT-LCD on Metal Foil Substrate	7-13
Figure 7.18 Physical Layout of Pixels with 2 TFTs	7-14
Figure 7.19: Performance of Poly-Si TFTs on Metal Foil	7-14
Figure 7.20: Transfer Process for TFT backplanes	7-15
Figure 7.21: (a) Transferred layer: (b) LTPS array on 0.2 mm plastic substrate	7-16
Figure 7.22: SUFTLA process steps	7-17
Figure 7.23: TFT backplane transferred to plastic substrate	7-17
Figure 7.24: I-V Characteristics of SUFTLA TFTs	7-17
Figure 7.25: OLED pixel structure with SUFTLA backplane	7-18
Figure 7.26: Pixel Circuit for AM-EPD on plastic substrate	7-18
Figure 7.27: Block diagram of AM-EPD	7-19
Figure 7.28: Improvements in Mobility of Organic Semiconductors	7-20
Figure 7.29: OLED Pixel Structure with Pentacene TFTs	7-21
Figure 7.30: Id versus Vgs and Vds for pentacene TFTs	7-21
Figure 7.31: OLED Structure and Emission with 16 Intensity Levels	7-21
Figure 7.32: TFT Structure and PES Substrate with Pentacene TFTs	7-22
Figure 7.33: I-V Characteristics: (a) without Surface Treatment; (b) with Treatment	7-23
Figure 7.34: Structure and I-V Characteristics of OTFT Made by OVPD	7-23
Figure 7.35: Grain Size in Pentacene Films: (a) on SiO ₂ ; (b) on Polyimide	7-24
Figure 7.36: I-V Characteristic of Pentacene Films: (a) on SiO ₂ ; (b) on Polyimide	7-24
Figure 7.37: Mobility and Grain Count for Pentacene on Various Underlayers	7-25
Figure 7.38: Polymer Aperture Mask and I-V Characteristics of Pentacene Transistors	7-26
Figure 7.39: Structure and I-V Characteristics of OTFT for Electrophoretic Display	7-26
Figure 7.40: Schematic of the fabricated PDLC cell	7-27
Figure 7.41: Transfer characteristics and transmission of the PDLC cell with OTFT backplane	7-28
Figure 7.42: Performance of Complementary Organic Circuits	7-29
Figure 7.43: Self-Assembled Monolayer Gate Dielectrics	7-29
Figure 7.44: SAM-TFT Characteristics	7-30
Figure 7.45: Relative Stability and Mobility of Organic Semiconductors	7-31
Figure 7.46: Improvements in Mobility of Organic Semiconductors	7-31
Figure 7.47: Performance of Organic TFTs	7-32
Figure 7.48: Organic TFTs with Double-layer Dielectrics	7-32
Figure 7.49: P3HT Transistor Characteristics in Air	7-33
Figure 7.50: Structure of Two Thiophenes	7-34
Figure 7.51: New Merck Terthiophene	7-34
Figure 7.52: Organic Material Set for Chip Printing at PolyIC	7-35
Figure 7.53: Organic Material Set for Chip Printing at PolyIC	7-35
Figure 7.54: Performance Variations in Polymer FETs	7-36
Figure 7.55: Sheet resistance of ITO deposited at room temperature	7-38
Figure 7.56: ITO surface structure as recorded by an Atomic Force Microscope	7-38
Figure 7.57: SEM micrograph of p-ITO surface annealed to (a) 1400C and (b) 2000C	7-39
Figure 7.58: Smoothness of Arylite substrate films	7-39
Figure 7.59: Strain Resistance of ITO on Plastic	7-40
Figure 7.60: Carbon nanotubes as First Formed and then Purified	7-41
Figure 7.61: CNT Optical Transmission versus Resistance and Wavelength	7-41
Figure 7.62: Tensile Stress Testing of ITO and CNT Films	7-42
Figure 7.63: Roll Fatigue Testing of ITO and CNT Films	7-42
Figure 7.64: Folding and Abrasion Tests of ITO and CNT Films	7-43
Figure 7.65: Transmittance of Ca-Ag Double Films on Glass Substrates	7-43
Figure 7.66: Particle Size and Resistivity of Conductive Inks	7-44

Figure 7.67: Structure of Printed Conductive Films	7-45
Figure 7.68: Sintering Temperature and Particle Size	7-45
Figure 7.69: Production Lines for Power Paper Cells	7-46
Figure 7.70: Structure of Button Cell and Thin Film Batteries	7-46
Figure 7.71: Voltage Decay Curves for Power Paper Batteries	7-47
Figure 7.72: Smart Paper Development at Power Paper	7-48
Figure 8.1: Demand Mode Ink-Jet Printing Technology	8-2
Figure 8.2: Scheme of interactions for ink jet printing requirements	8-2
Figure 8.3: Structure of a piezo micro deposition system	8-3
Figure 8.4: PZT Drop-on-Demand Generating Device	8-4
Figure 8.5: Droplets with PPV in Solution	8-5
Figure 8.6 Variation in jet direction for stainless steel and nickel nozzle plates	8-5
Figure 8.7 Directional control in 128-nozzle ink-jet head	8-6
Figure 8.8: Cross Section of an Individual Jet	8-6
Figure 8.9: Nozzle Orifice	8-7
Figure 8.10: Integrated Etched Filter	8-7
Figure 8.11: Drop Control of Nickel Head and Silicon Head	8-7
Figure 8.12: SX-128 Piezo Inkjet Head	8-9
Figure 8.13: "MACH" and "LMChips" heads	8-9
Figure 8.14: Ink chambers in micro-piezo heads	8-10
Figure 8.15: Variation in drop position on substrate	8-10
Figure 8.16: Drop formation for a normal (Newtonian) liquid (top images) and a solution with high molecular weight polymers added (bottom images)	8-12
Figure 8.17: AFM (phase as insert) of ink jetted films of polymer blend (left) and single component material (right)	8-13
Figure 8.18: Microbank structures to define sub-pixels	8-14
Figure 8.19: Microbank structures after filling	8-14
Figure 8.20: Bank structures for AM-OLED without cathode separation	8-14
Figure 8.21: SEM images of fabricated mold (a) and transferred pixel array patterns (b) with 10x10 μm^2 squares	8-15
Figure 8.22: Self-aligned bank formation process	8-15
Figure 8.23: Lines Formed by Thermal Laser Imaging Followed by Inkjet Printing	8-16
Figure 8.24: Surface Controlled Critical Dimensions	8-16
Figure 8.25: Film Uniformity Achieved by Pre-deposition Surface Treatment	8-17
Figure 8.26: Wetting Effects of Plasma Treatment	8-17
Figure 8.27: Effect of Surface Pre-Treatment on PEDOT Film Formation	8-17
Figure 8.28: Self Assembling Patterning of Source-Drain Pairs with Surfactants	8-18
Figure 8.29: Source-Drain Lines Separated by Plasma Treatment	8-18
Figure 8.30: Source-Drain Lines Separated by Plasma Treatment	8-19
Figure 8.31: Organic TFT Printed Using Self Assembled Source and Drain	8-19
Figure 8.32 Tests of Printed Active Matrix Array of Organic TFTs	8-19
Figure 8.33: Drop positioning depends upon directional control and throw distance	8-20
Figure 8.34: Tail accretion due to surface tension	8-21
Figure 8.35: Nozzle-to-nozzle variation in drop velocity	8-22
Figure 8.36: Effect of Real-Time Control on Drop Velocity	8-22
Figure 8.37: Droplet Volume Variation after DPN Correction	8-23
Figure 8.38: Ink-jet systems for RGB LEP printing installed at Philips	8-23
Figure 8.39: Multiple Drop Deposition from Inclined Head Arrays	8-24
Figure 8.40: Array of 100 x 300 μm pixels printed using 50 μm diameter drops	8-24
Figure 8.41: Comparison of efficiency- voltage characteristics of spin coated and ink -jet printed devices using the same LEP materials	8-25

Figure 8.42: Bottom contact OTFTs fabricated by ink-jet printing	8-26
Figure 8.43: Consistency of I-V Characteristics for Ink-jet Printed OTFTs	8-26
Figure 8.44: Organic TFT Arrays by Additive Printing	8-27
Figure 8.45: Diagram for LITI Optical Imaging System	8-28
Figure 8.46: Schematics of the LITI Process	8-29
Figure 8.47: Force Balance During LITI Transfer	8-30
Figure 8.48: LITI Patterned Stripes: (a) LEP, (b) LEP/SM Blend, (c) Small Molecule	8-31
Figure 8.49: SEM Images of Printing Plates	8-32
Figure 8.50: Thermal Transfer of Color Filter Pigments	8-33
Figure 8.51: Color Pigment Deposition onto a Black Matrix Framework	8-33
Figure 8.52: Flat Bed Scanner for Thermal Transfer onto Glass Substrates	8-34
Figure 8.53 TFT Patterning Using Laser Transfer	8-35
Figure 8.54: Bus Structures Printed by Thermal Multi-Layer Patterning	8-35
Figure 8.55: Micro-imprint Process and Structures Printed in PMMA at 1700C and 10 MPa	8-37
Figure 8.56: Conducting structures produced by micro-contact printing	8-38
Figure 8.57: Screen Printing through Woven Mesh	8-40
Figure 8.58: Processes for Printing OTFTs	8-40
Figure 8.59: Flexographic Printing	8-41
Figure 8.60 Dot Structures on Printing Plates and Image	8-41
Figure 8.61: Gravure Printing	8-42
Figure 8.62: Profiles of Ink Dots Formed by Contact Printing	8-42
Figure 8.63: Offset Printing Process	8-43
Figure 8.64: Outer Layers of Blanket Roller	8-43
Figure 8.65: Ink Transfer Mechanism in Offset Printing	8-44
Figure 9.1: R-2-R Manufacturing of OLED displays	9-1
Figure 9.2: Volume versus Cost Relationship for R-2-R Manufacturing	9-2
Figure 9.3: Roll-to-Sheet Fabrication of PDLC Panels	9-2
Figure 9.4: R-2-R Manufacturing Tool Layout	9-3
Figure 9.5: Removable Compartments for Magnetron Sputtering	9-3
Figure 9.6: R-2-R Vacuum Deposition System with 10 Chambers	9-4
Figure 9.7: Conceptual R-2-R Manufacturing Line Layout	9-5
Figure 9.8: Effects of Registration Errors in Web Processing	9-5
Figure 9.9: Lateral Motion to Match Web with Tool	9-6
Figure 9.10: Friction Control in Winding and Unwinding	9-6
Figure 9.11: Winding Roller with Teetering	9-7
Figure 9.12: Wrinkling Cause by Web Compression	9-7
Figure 9.13: Edge and Center Deformations	9-8
Figure 9.14: Wound Roll Defects	9-8
Figure 9.15: Tension Control System	9-8
Figure 9.16: Tension Control with One-Face Contact	9-9
Figure 9.17: Tension and Web Speed Control	9-9
Figure 9.18: Structure and Process Selection for Organic TFTs	9-10
Figure 9.19: Flexible Circuits Fabricated by R-2-R	9-10
Figure 9.20: Process Status for R-2-R Production of Poly-Si TFTs	9-11
Figure 9.21: Magnetron for Surface Preparation	9-11
Figure 9.22: SmartWeb PVD systems	9-13
Figure 9.23: Linear Evaporator for Organic Materials	9-13
Figure 9.24: Linear Microwave Plasma Source (2.45GHz)	9-14
Figure 9.25: R-2-R Vacuum Deposition System for Polymer Coating	9-14
Figure 9.26: R-2-R UV Lithography System	9-16
Figure 9.27: Reel-to-Reel Lithography	9-16

Figure 9.28: Chromium/Copper Metallization	9-16
Figure 9.29: Basic Imprint Lithographic Process and Sample Products	9-17
Figure 9.30: SAIL Demonstration; Al Lines Crossing Over Cr Lines	9-18
Figure 9.31: Imprint Lithography in a R-2-R Environment (Hewlett Packard)	9-18
Figure 9.32: Screen printer with belt oven and UV curing	9-19
Figure 9.33: Measurement of Via Contacts	9-20
Figure 9.34: Deposition through Shadow Mask onto Web	9-20
Figure 9.35: Continuous Web Inspection	9-21
Figure 9.36: Removal of Periodic Pattern from Panel Image	9-22
Figure 9.37: Pipeline Processing for Web Inspection	9-22
Figure 9.38: In-line Measurement of Optical Density	9-23
Figure 9.39: Web Measurements of Transmittance and Reflectance	9-23
Figure 9.40: High Precision Eddy-Current Measurement System	9-24
Figure 9.41: Layout of USDC Web Processing Tool	9-25
Figure 9.42: Defect Measurement on USDC Web Processing System	9-26
Figure 9.43: Defect Density Reduction during Development of Web Handling Tool	9-26
Figure 9.44: R2R Cost Breakdown at 100k sq ft/week	9-29
Figure 9.45: R2R Cost Breakdown at Two Volume Levels	9-29
Figure 9.46: Roadmap for FlexiDis Project	9-40
Figure 9.47: Structure of a-Si Photovoltaic Panels	9-41
Figure 9.48: R2R Photovoltaic Deposition Line and Fabricated Roll	9-43
Figure 9.49: Structure of a-Si Solar Cell on Stainless Steel Substrate	9-44
Figure 9.50: Schematic of PECVD Deposition Line	9-44
Figure 9.51: Side View of PECVD Deposition Line	9-45
Figure 9.52: Basic Principle of RFID Systems	9-46
Figure 9.53: Price Sensitivity of RFID Market (Units per Year)	9-46
Figure 9.54: 4-bit Transponder Chip	9-47
Figure 9.55: 125 kHz Polymer Rectifier	9-47
Figure 9.56: Examples of NanoBlockIC®	9-48
Figure 9.57: Preparation of Nano-block Receptors in Plastic Substrate	9-48
Figure 9.58: Dispensing Nano-blocks from Fixed Nozzles onto Moving Substrate	9-49
Figure 9.59: R-2-R Line for Fluidic Self Assembly	9-49
Figure 9.60: Fabrication of Nano-block Interconnects	9-50
Figure 9.61: RFID tags on Plastic Backing Roll	9-50

Table of Tables

Table 1.1 Annual Generation of Original Information	1-4
Table 1.2 Table: Typical Processing Costs for Unit Sets and Flat Forms	1-8
Table 1.3 Table: Annual Forms Expenditures by Company Size	1-9
Table 1.4 Reported Values of Reflectivity and Contrast	1-16
Table 1.5 Table: Resolution of Common Printed Items	1-18
Table 1.6 Time-to-Visibility Data for Various Displays in Office and Outdoor Light Conditions	1-19
Table 2.1 Table: Estimates of Total Available Markets for Flexible Electronics	2-1
Table 2.2 Sample Specifications for Smart Tickets	2-10
Table 2.3 Forecast Unit Sales of Displays for E-Books (1000s)	2-17
Table 2.4 Forecast Revenues of Displays for E-Books (\$M)	2-18
Table 2.5 UK Outdoor Advertisers by Revenue and Capitalization	2-22
Table 2.6 Typical Gross Invoice Value from Outdoor Advertising	2-23
Table 2.7 Table: Number of U. S. Locations for Outdoor Displays	2-23
Table 2.8 Forecasted Sales of Vacuum Fluorescent Displays (1000 units)	2-31
Table 2.9 Forecasted Sales of Vacuum Fluorescent Displays (\$M)	2-31
Table 2.10 Video Displays in Vehicles	2-32
Table 2.11 Video Displays in Vehicles by Technology	2-32
Table 3.1 Comparison of Reflective Display Performance	3-3
Table 3.2 Environmental Tests of Electrophoretic Displays	3-16
Table 3.3 Status of Gyricon Display Development (April 2004)	3-23
Table 3.4 Characteristics of Commotion Displays	3-31
Table 3.5 Potential Applications of Commotion Displays	3-32
Table 3.6 Performance of Colored iMoDTM Displays	3-33
Table 3.7 Relative Performance of iMoDTM and Reflective LCD Displays	3-34
Table 3.8 Switching Speeds of Early Prototype Panels	3-44
Table 3.9 Contrast Ratio and Reflectivity of Electronic and Natural Paper	3-45
Table 4.1 Table: Properties of passive matrix OLEDs on plastic	4-3
Table 6.1: Typical Parameter Values for Plastic Substrates	6-3
Table 6.2: Coefficient of Thermal Expansion for Teonex ® Q65	6-7
Table 6.3: Chemical Resistance of Teonex ® Q65 and Other Films	6-13
Table 7.1 Switching Requirements for Four Bistable Displays	7-1
Table 7.2: Characteristics of a-Si TFTs on Glass and Plastic	7-6
Table 7.3 : Comparison between ULTPS process with standard silicon CMOS (ULSI)	7-10
Table 7.4: Parameter Variation for pMOS Process over a 6" Wafer	7-13
Table 7.5: Performance of Power Paper Batteries	7-47
Table 8.1: Process Techniques for Organic Electronics: Development Phase	8-1
Table 8.2: Display requirements and ink-jet printing system attributes	8-3
Table 8.3: Desired performance parameters for IJP heads	8-4
Table 8.4: Effect of gap and directional control on placement accuracy (red numerals) in μm	8-20
Table 8.5: LITI PLED Performance	8-31
Table 8.6: Improvements in Flat Bed Scanner Design	8-34
Table 8.7: Capabilities of Traditional Printing Processes	8-39
Table 9.1: Optical Films Suitable for Sputter Deposition	9-12
Table 9.2: Deposition Rates for Optical Films in Dual Magnetrons	9-12
Table 9.3: Advantages of Imprint Lithography	9-19
Table 9.4: Process Yield Assumptions	9-30
Table 9.5: Timeline for Technical Development at CAMM	9-32
Table 9.6: Diagnostic Systems in Photovoltaic Production	9-45